查询MAX4141供应商







330MHz, 4x1 Precision Video Multiplexer

General Description

The MAX4141 is a wideband 330MHz, 700V/µs 4x1 multiplexer optimized for high-definition, broadcastquality, composite (HDTV, NTSC, PAL, SECAM) video switching arrays. The device includes four open-loop buffer amplifiers with a 0.1dB gain flatness of 150MHz, and enable and switch-control logic. The MAX4141 operates from ±5V supplies and features differential phase and gain error of only 0.01°/0.01%. The ultra-low switching glitch (less than 13mV) is positive to avoid confusion with any sync pulses.

Ideal as a building block for large switch arrays, the MAX4141 features a constant, high input impedance and a disable function that puts the output into a highimpedance state and reduces the operating current to only 250µA. The open-loop architecture allows the output to drive capacitive loads without oscillation.

Other key features include -66dB crosstalk (30MHz), -74dB isolation (30MHz), less than 10mV offset voltage, and a 110MHz full-power bandwidth (1.4Vp-p). The MAX4141 is available in a 14-pin narrow SO package.

Broadcast/HDTV-Quality Color Signal Multiplexing

- Features
- 330MHz -3dB Bandwidth
- ♦ 0.1dB Gain Flatness of 150MHz
- 700V/µs Slew Rate
- 0.01°/0.01% Differential Phase/Gain
- + -66dB Crosstalk and -74dB Isolation at 30MHz WWW.DZSC.CO
- High-Z Outputs when Disabled
- + 3pF Input Capacitance
- Low Switching Glitch

IN0 0

IN1 0

IN2

IN3 0

A0 0

A1

EN O

On-Board Control Logic

Ordering Information

Functional Diagram

PART	TEMP. RANGE	PIN-PACKAGE
MAX4141CSD	0°C to +70°C	14 SO



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Applications

Maxim Integrated Products 1

CONTROL

LOGIC

ABSOLUTE MAXIMUM RATINGS

Vcc
V _{FF} 6V
V _{CC} -V _{EE}
Analog Input Voltage(VEE - 0.3V) to (VCC + 0.3V)
Digital Input Voltage0.3V to (V _{CC} + 0.3V)
Duration of Short Circuit to GroundContinuous (Note 1)

Continuous Power Dissipation (T _A = +70°C	2)
SO (derate 8.00mW/°C above +70°C)	640mW
Operating Temperature Range	0°C to +70°C
Storage Temperature Range	65°C to +160°C
Junction Temperature	+150°C
Lead Temperature (soldering, 10sec)	+300°C

Stresses beyond those listed under "Absolute Maximum Ratings" may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated in the operational sections of the specifications is not implied. Exposure to absolute maximum rating conditions for extended periods may affect device reliability.

ELECTRICAL CHARACTERISTICS

Note 1: If maximum power-dissipation rating is met.

 $(V_S=\pm 5V, -2.5V \le V_{IN} \le +2.5V, R_L = 5k\Omega, C_L = 5pF, T_A = 0^{\circ}C \text{ to } +70^{\circ}C, \text{ unless otherwise noted. Typical values are at } T_A = +25^{\circ}C.)$

PARAMETER	SYMBOL	CONDITIONS		MIN	TYP	MAX	UNITS
DC PARAMETERS							
Operating Supply Voltage	VS			±4.5	±5.0	±5.5	V
Operating Supply Current	IS(ON)	Enabled	$T_A = +25^{\circ}C$		5.0	5.5	- mA
	IS(ON)		TA = TMIN to TMAX			6.5	
Disabled Supply Current	IS(OFF)				250	350	μΑ
Input Voltage Range	VIN			±2.5			V
Input Bias Current	Ip	VIN = 0V	Channel selected		±2.5	±4.0	- μΑ
	IB		Channel disabled		±0.2		
Input Resistance	RIN	Channel selected Channel disabled			0.4		МО
					100		11122
Input Capacitance	CIN	$V_{IN} = 0V$, channel enabled or disabled			3		pF
Output Offsot Voltago	Vos	$T_A = +25^{\circ}C$			±3	±10	mV
	VUS	$T_A = T_{MIN}$ to T_{MAX}				±15	
Power-Supply Rejection Ratio	PSRR	$V_{S} = \pm 4.5 V \text{ to } \pm 5.5 V$		50			dB
Voltage Gain	Av	$V_{IN} = \pm 2.5 V$	$T_A = +25^{\circ}C$	0.98		1.0	- V/V
			T _A = T _{MIN} to T _{MAX}	0.97		1.0	
Output Resistance	Rout				20		Ω
Disabled Output Current	IOUT(OFF)	Vout = 0V			10		nA
Disabled Output Resistance	Rout				30		MΩ
Disabled Output Capacitance	COUT				5		pF
Logic Input High Voltage	Vinh	$V_{S} = \pm 4.5 V \text{ to } \pm 5.5 V$		2.0			V
Logic Input Low Voltage	Vinl	$V_{S} = \pm 4.5 V \text{ to } \pm 5.5 V$				0.8	V
Logic Input High Current	linh	$V_{S} = \pm 4.5 V$ to $\pm 5.5 V$				10	μA
Logic Input Low Current	IINL	$V_S = \pm 4.5 V$ to $\pm 5.5 V$				10	μA

$(V_S=\pm 5V, -2.5V \le V_{IN} \le +2.5V, R_L=5k\Omega, C_L=5pF, T_A=0^\circ C \text{ to } +70^\circ C, \text{ unless otherwise noted}. Typical values are at T_A=+25^\circ C.)$ CONDITIONS PARAMETER SYMBOL MIN TYP MAX UNITS AC PARAMETERS $V_{IN} = 5Vp-p$ 700 Slew Rate SR V/µs $V_{IN} = 1.4Vp-p$ 500 $V_{IN} = 1.4 Vp-p$ 110 Full-Power Bandwidth MHz **f**PBW (Note 2) $V_{IN} = 5Vp-p$ 45 -3dB Bandwidth $V_{IN} = 0.1 V p - p$ 330 MHz f3dB DC to 30MHz 0.02 Gain Flatness dB DC to 150MHz ±0.1 dR Gain Peaking 0.08 $V_{IN} = 0.2Vp-p$, 10% to 90% Small-Signal Rise Time t_R 950 ps Differential Gain (Note 3) DG f = 3.58MHz0.01 % Differential Phase (Note 3) DP f = 3.58MHz0.01 degrees $V_{IN} = 1V p$ -p, f = 30MHz, R_{IN} = 50 Ω All-Hostile Crosstalk 66 dB Off Isolation VIN = 1Vp-p, f = 30MHz 74 dB Channel Switching Off Time toff 1.0 μs Channel Switching On Time 500 ton ns Switching Transient 13 mVp-p f = 3.58MHz Group Delay 860 ps Input-Output Delay Matching Chip-to-chip, f = 3.58MHz ±0.2 degrees Second Harmonic Distortion $f = 30MHz, V_{IN} = 1.4Vp-p, R_L = 2k$ -65 dBc Third Harmonic Distortion f = 30MHz, VIN = 1.4Vp-p, RL = 2k -70 dBc

Note 2: Full-Power Bandwidth is inferred from Slew Rate (SR) testing by the equation SR = ω Ep, where Ep is the peak output voltage and $\omega = 2\pi f$.

Note 3: Differential Gain and Phase are tested using a modulated ramp, 100IRE (0.714V).

ELECTRICAL CHARACTERISTICS (continued)







M/IXI/N

Pin Description

4
4
X
2

PIN	FUNCTION	DESCRIPTION
1	INO	Signal Input
2, 4, 6	GND	Analog (Signal) Ground. Since inputs are isolated by these grounds, they should be as noise-free as possible.
3	IN1	Signal Input
5	IN2	Signal Input
7	IN3	Signal Input
8	N.C.	No Connect—not internally connected.
9	EN	Output Enable and device shutdown. A logic high on this pin enables the output. A logic low causes the output to assume a high-impedance state and reduces operating current.
10	V _{EE}	Negative Power-Supply Voltage. Decouple to power ground.
11	OUT	Signal Output
12	V _{CC}	Positive Power-Supply Voltage. Decouple to power ground.
13	A1	Channel Selection Bit. See truth tables.
14	A0	Channel Selection Bit. See truth tables.

_Detailed Description

The MAX4141 video switch is manufactured with Maxim's proprietary complementary bipolar process that yields high bandwidth and low capacitance. To maintain a wide bandwidth, the MAX4141 incorporates a straightforward structure of input and output buffers. Make-before-break switching is employed to reduce noise and glitches, even when switching from part to part in large arrays. The input buffers provide a constant, high input impedance. And, they prevent the make-before-break action from feeding back to the input and causing noise and/or glitches.

The design of the switching mechanism limits the inevitable glitch to within 13mVp-p. In addition, the glitch pulse is positive to avoid confusion with any negative sync pulses.

Unity-gain output buffers isolate other inputs from the switching action of large multiplex arrays. These buffers can drive $5k\Omega$ resistive loads. Load capacitance is limited only by system bandwidth requirements.

The MAX4141 does not contain buffer latches. The digital inputs control the switch transparently.

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_Applications Information

Grounding, Bypassing, and PC Board Layout

In order to obtain the MAX4141's full 330MHz bandwidth, Microstrip and Stripline techniques are recommended in most cases. To ensure your PC board does not degrade the switch's performance, it's wise to design the board for a frequency greater than 1GHz. Even with very short runs, it's good practice to use this technique at critical points, such as inputs and outputs. Whether you use a constant-impedance board or not, observe the following guidelines when designing the board:

- Do not use wire-wrap boards, because they are too inductive.
- Do not use IC sockets. They increase parasitic capacitance and inductance.
- In general, surface-mount components have shorter leads and lower parasitic reactance, and give better high-frequency performance than through-hole components.
- The PC board should have at least two layers, with one side a signal layer and the other a ground plane.
- Keep signal lines as short and as straight as possible. Do not make 90° turns; round all corners.
- The ground plane should be as free from voids as possible.

M/IXI/N

On Maxim's evaluation kit, the ground plane has been removed from areas where keeping the trace capacitance to a minimum is more important than maintaining ground continuity. For example, the ground plane has been removed from beneath the IC to minimize pin capacitance.

The signal input line is approximately 0.103 inches wide to minimize inductance and to provide a constant 50 Ω impedance path. It is terminated by a 50 Ω chip resistor.

Bypass Components—Capacitors Electrolytic and tantalum capacitors are available from 0.1µF to over 300µF, but have resonant frequencies below 1MHz. Ceramic capacitors are highly recommended and are available to 1µF, with the smaller values having resonant frequencies to almost 1GHz. The less expensive capacitors are constructed using a multilayer approach; high values are available, but resonant frequencies beyond a few hundred megahertz are not, because of the inductive effect of the multiple layers. More expensive, solid dielectric microwave porcelain/ceramic capacitors are available up to 1000pF with resonant frequencies beyond 20GHz. In all types, resonant frequency depends on capacitor value, voltage rating, and physical size; the larger the capacitor, the lower the resonant frequency.

We recommend ceramic surface-mount/chip capacitors. Placement of bypass capacitors on the PC board is critical, and the smaller chip capacitors allow placement as close to the part as practical. The smaller, higher frequency capacitors should be placed as close to the chip as possible, with the higher-value capacitors placed farther away.

Creating Large Arrays

The MAX4141 was designed as a building block for large arrays. The high-power drive required for internal cable drivers has a negative effect on crosstalk and increases system power consumption. Figure 1 shows an 8x1 multiplexer circuit.

Even though the MAX4141 drives capacitive loads, you may want to limit the number of switches connected together to maximize bandwidth. The MAX4141 has a finite input capacitance of about 3pF and a dynamic output resistance of about 20 Ω . This causes a pole at a little more than 2.6GHz. However, in a large array with many switch inputs, the total capacitance is (N x 3pF), where "N" is the number of switches connected in parallel. The pole will be located at:

$$\frac{1}{2\pi \times (N \times 3pF + C_{STRAY}) \times 20\Omega} MHz$$

where $\ensuremath{\mathsf{CSTRAY}}$ is the stray capacitance from the interconnect.

If the maximum number of switches that may be connected while still maintaining bandwidth is less than your system requirements, use a unity-gain buffer amplifier to isolate the switch from the remainder of the inputs.

Table 1. Truth Table

A1	A0	EN	OUT
Х	Х	0	High-Z
0	0	1	INO
0	1	1	IN1
1	0	1	IN2
1	1	1	IN3

M/IXI/N



Figure 1. 8x1 Multiplexer Circuit

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